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ABSTRACT OF THE DISCLOSURE

The present invention aims to provide a fan-motor-incorporated heat sink capable of effectively supplying air flow for cooling even if there is no sufficient space above the heat sink as the result of thinning an electronic device.

In order to attain the object, a heat sink according to the present invention obtains a sufficient space for taking in air above the heat sink by making a fan, the fins of a heat sink substrate and the side wall thereof lower than driving means such as a motor and the like which are structurally restricted in thickness. In addition, the heat sink substrate and the fins are formed such that air is exhausted only in one direction and a cover is provided on the side of the heat sink substrate on which a motor is mounted and to which air is taken in to prevent exhausted air from being taken in.

With this arrangement, it is possible to arrange the structure of the electronic device close to the upper surface of the motor on the heat sink, thereby facilitating the installation of the heat sink on a thinned electronic device and improving the effect of cooling a heat emitting element.

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